

Lonten N-channel 60V, 83A, 3.6mΩ Power MOSFET

Description

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- 60V,83A, $R_{DS(on),max} = 3.6 \text{m}\Omega @V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- Green device available

Applications

- Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

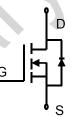
Product Summary

 $\begin{array}{ll} V_{DSS} & 60V \\ R_{DS(on),max} \textcircled{@} \ V_{GS} \text{=} 10V & 3.6 \text{m} \Omega \\ I_D & 83A \end{array}$

Pin Configuration









Plb

Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Continuous drain current (Tc = 25°C)		83	A
(T _C = 100°C)	l _D	60	A
Pulsed drain current ¹⁾	I _{DM}	249	A
Gate-Source voltage	V _{GSS}	±20	V
Avalanche energy ²⁾	Eas	11	mJ
Power Dissipation	P _D	57	W
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	2.2	°C/W
Thermal Resistance Junction-to-Ambient	R _{0JA}	55	°C/W

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Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel	
LSGN06R036WB	DFN5X6	06R036WB	5000	

Flectrical Characteristics T. = 25°C unless otherwise noted

Electrical Characteristics	T _J = 25°C unle	ess otherwise noted				
Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						•
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	60			V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.2	1.7	2.5	V
Drain-source leakage current	I _{DSS}	V _{DS} =60 V, V _{GS} =0V			1	μΑ
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V			100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V			-100	nA
Design and the market and		V _{GS} =10 V, I _D =20 A		2.8	3.6	mΩ
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =4.5V, I _D =20 A		3.9	5.4	
Forward transconductance	g _{fs}	V _{DS} =5V , I _D =20A		66		S
Dynamic characteristics						
Input capacitance	C _{iss}	V 20 V V 2 2 V		3511		
Output capacitance	Coss	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$		1176		pF
Reverse transfer capacitance	C _{rss}	F = 1MHz		67		
Turn-on delay time	t _{d(on)}			20.3		
Rise time	tr	V_{DD} = 30V, V_{GS} =10V, I_D = 20A R_G =3 Ω		9.6		ns
Turn-off delay time	t _{d(off)}			61		
Fall time	t _f			15.2		
Gate resistance	Rg	V _{GS} =0 V,V _{DS} =0 V, F=1MHz		1.1		Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V 00V I 00A		15.5		
Gate to drain charge	Q_{gd}	V _{DS} =30V, I _D =20A,		9.5		nC
Gate charge total	Qg	- V _{GS} = 10 V		46		
Drain-Source diode characteristi	cs and Maxi	mum Ratings				
Continuous Source Current	ls				47.5	Α
Pulsed Source Current ³⁾	I _{SM}				142.5	Α
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A, T _J =25℃			1.2	V
Reverse recovery time	t _{rr}	L = 20A dL /dt= 100 A/up		24		ns
Reverse recovery charge	Qrr	- I _F =20A,dI _F /dt=100 A/μs		85		nC

Notes:

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^{1:} Repetitive Rating: Pulse width limited by maximum junction temperature.

^{2:} V_{DD} =50V, V_{GS} =10V, L=0.1mH, I_{AS} =15A, Starting T_J =25 $^{\circ}$ C.

^{3:} Pulse Test: Pulse Width $\leq 300~\mu$ s, Duty Cycle $\leq 2\%$.



Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

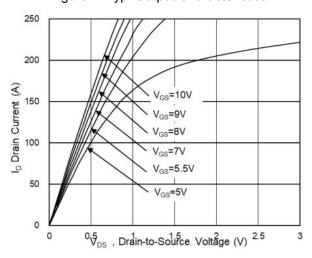


Figure 3. Capacitance Characteristics

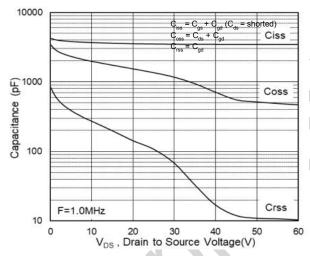


Figure 5. Body-Diode Characteristics

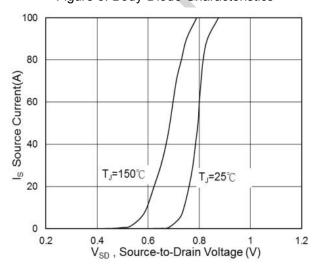


Figure 2. Transfer Characteristics

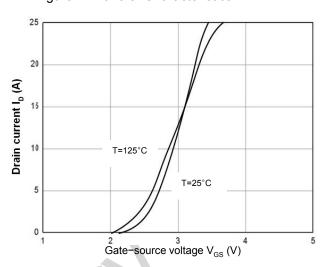


Figure 4. Gate Charge Waveform

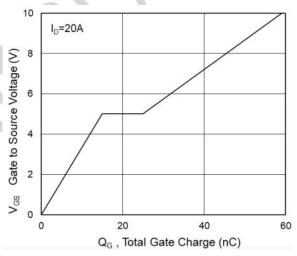


Figure 6. Rdson-Drain Current

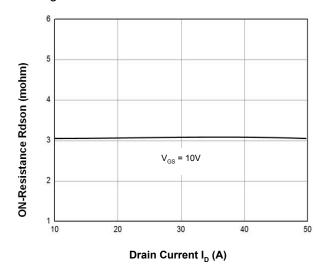




Figure 7. Rdson-Junction Temperature

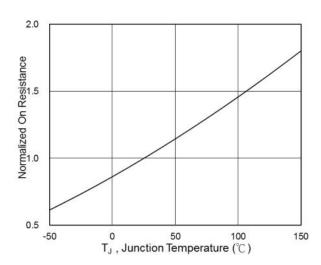


Figure 8. V_{GS(th)}-Junction Temperature

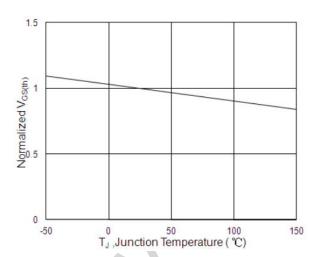


Figure 9. On-Resistance vs. Gate-to-Source voltage

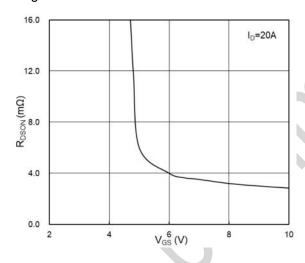


Figure 10: Safe Operating Area

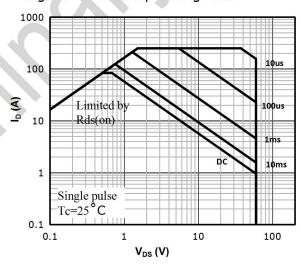
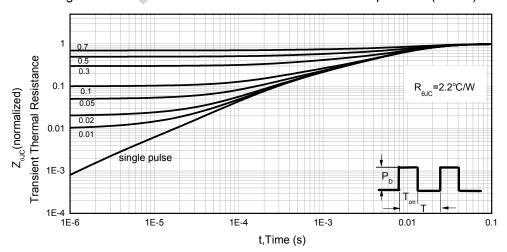


Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)

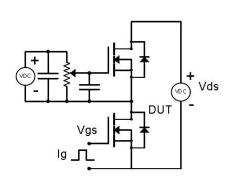


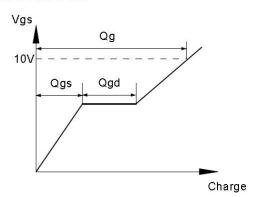
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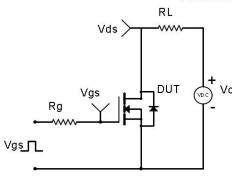
Test Circuit & Waveforms

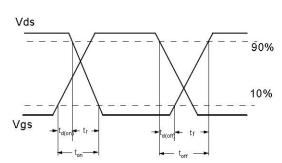
Gate Charge Test Circuit & Waveform



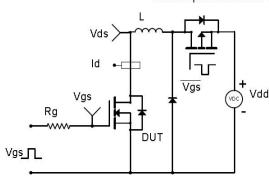


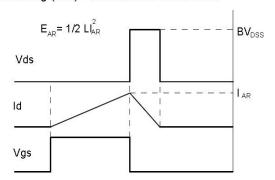
Resistive Switching Test Circuit & Waveforms



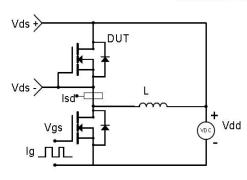


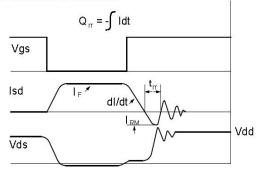
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





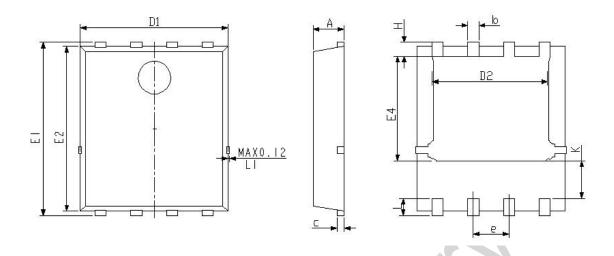
Diode Recovery Test Circuit & Waveforms







Mechanical Dimensions for DFN5 \times 6



DIMENSIONS	IONS IN MILLITMETERS		DIMENSIONS IN INC		
SYMBOL	MIN	MAX	MIN	MAX	
A	0.85	1. 20	0.033	0.047	
b	0.30	0. 51	0.012	0.020	
С	0. 15	0. 35	0.006	0.014	
D1	4.80	5. 40	0. 189	0. 213	
D2	3. 70	4. 55	0. 146	0. 179	
E1	5. 95	6. 35	0. 234	0. 250	
E2	5. 45	6.06	0. 215	0. 239	
E4	3. 30	3. 92	0. 130	0. 154	
e	1. 27BSC		0. 05BSC		
L	0.3	0. 71	0.012	0.028	
Н	0.38	0. 71	0.015	0.028	
K	1. 15	1. 45	0.045	0.057	



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